

Figure 1

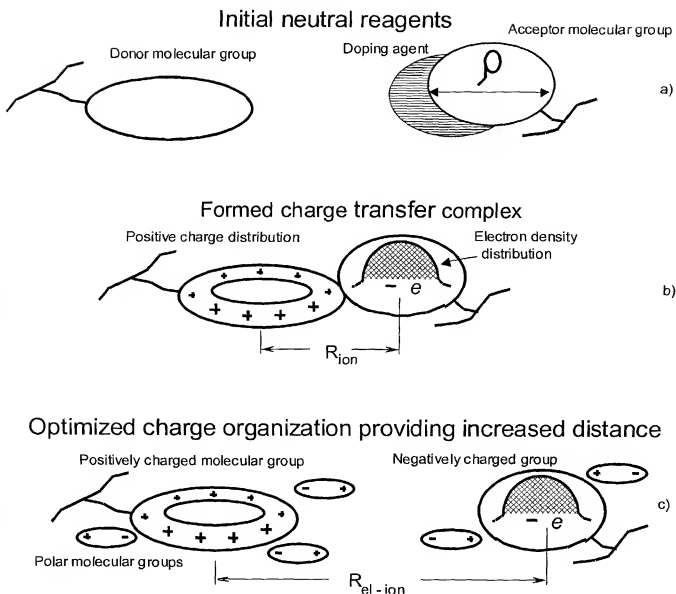


Figure 2

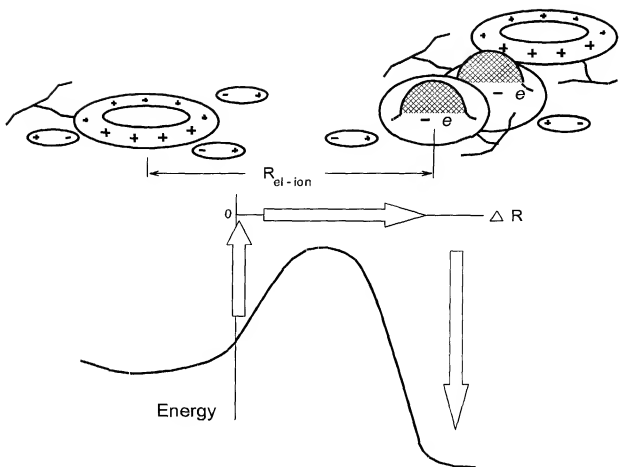


Figure 3

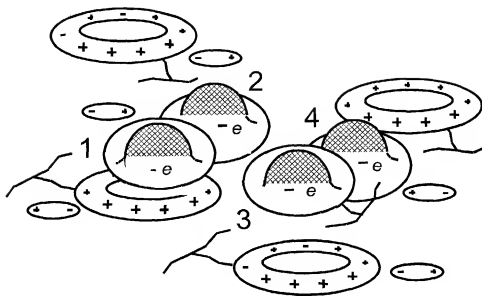


Figure 4



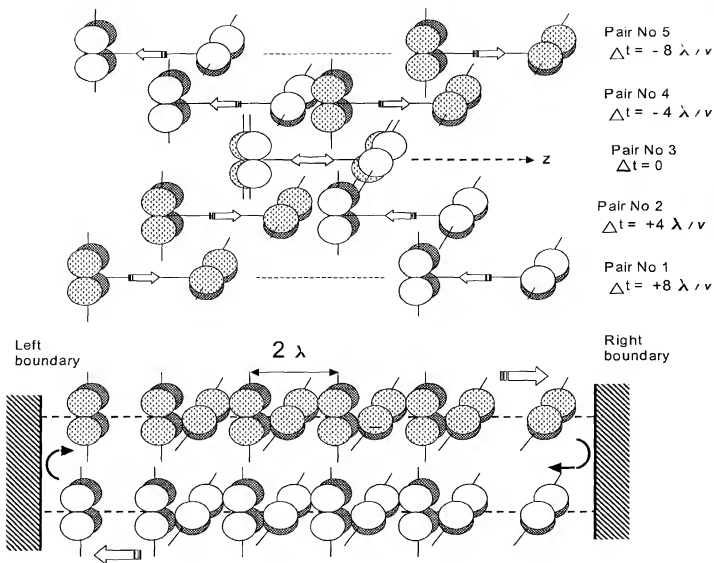


Figure 6

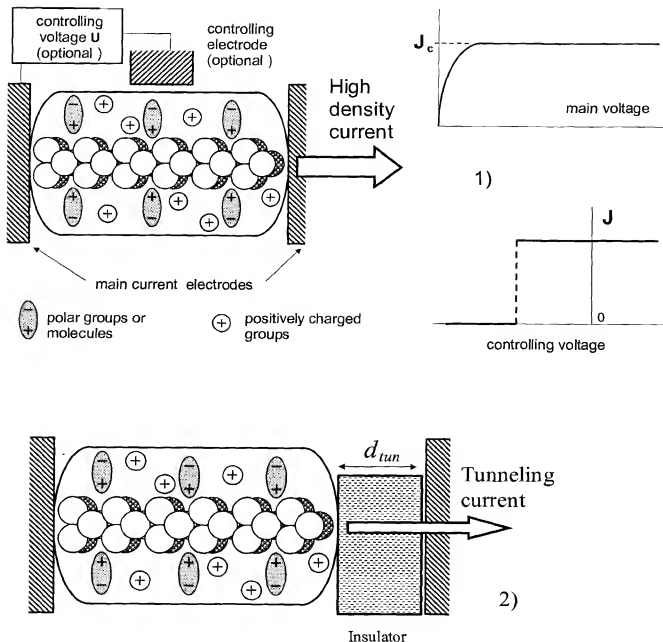


Figure 7

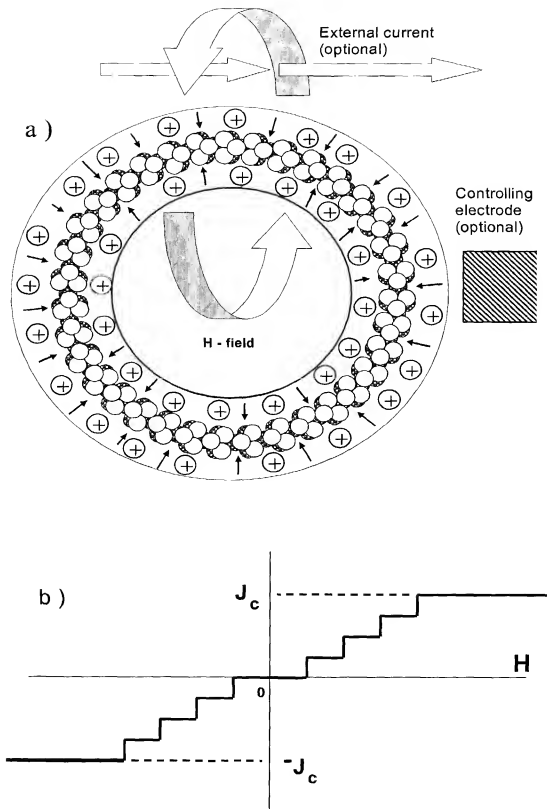


Figure 8

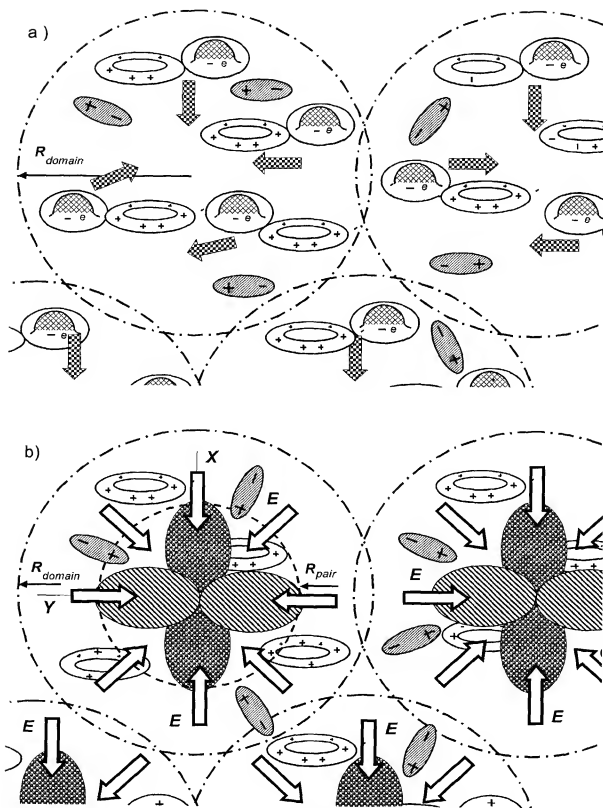
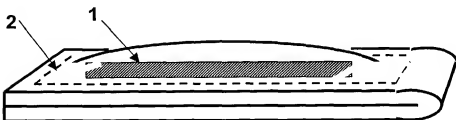


Figure 9



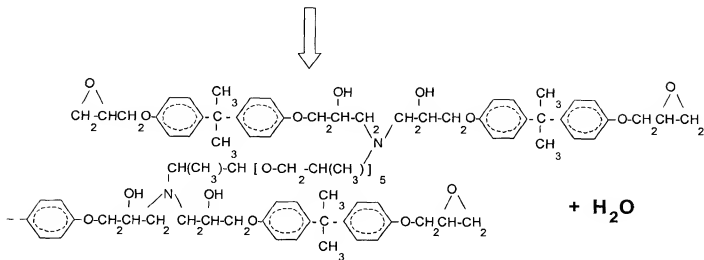
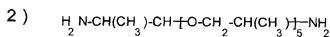
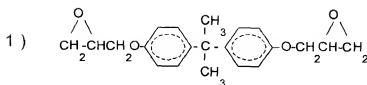


Figure 12

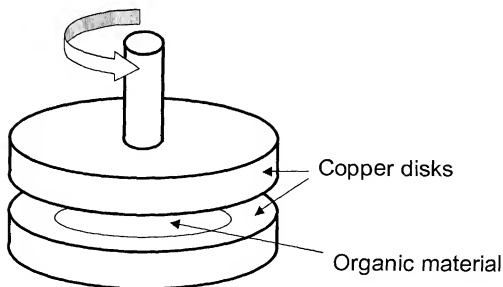


Figure 13

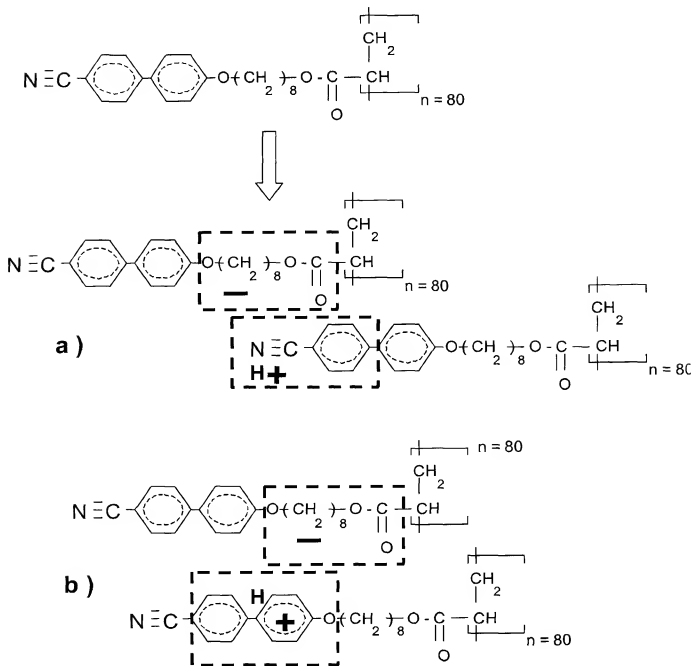


Figure 14

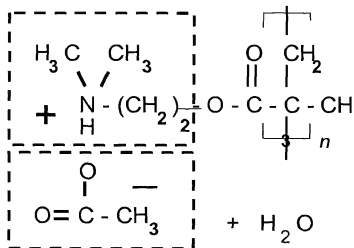


Figure 15

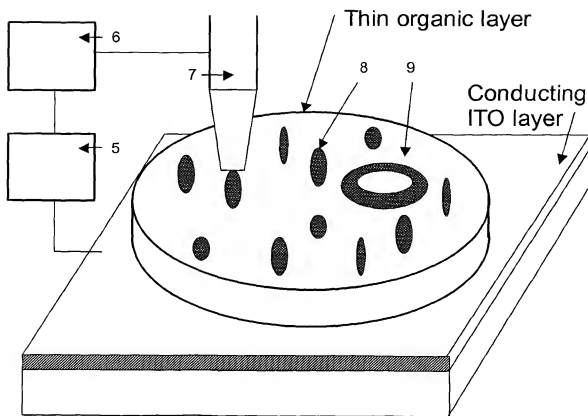


Figure 16

Hollow channels with $d = 500 - 1000 \text{ nm}$

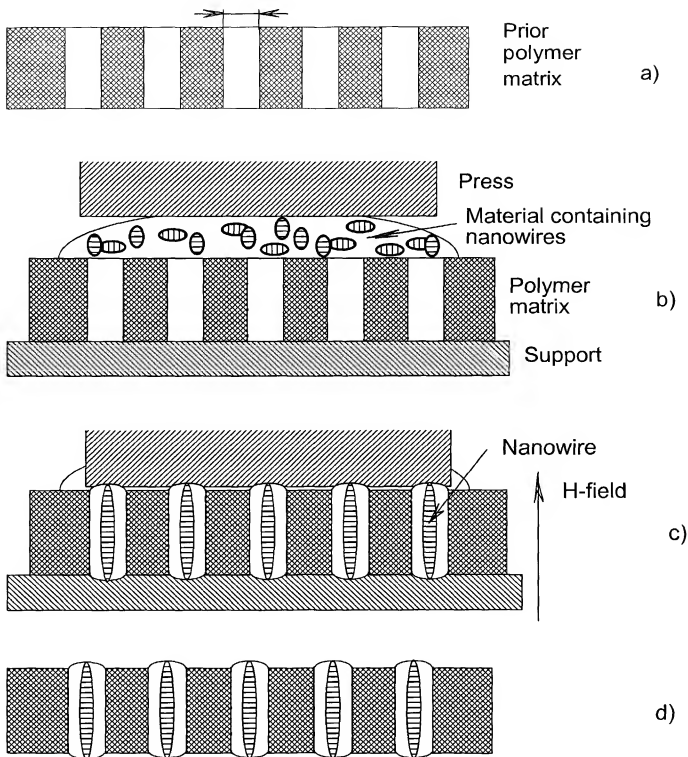


Figure 17

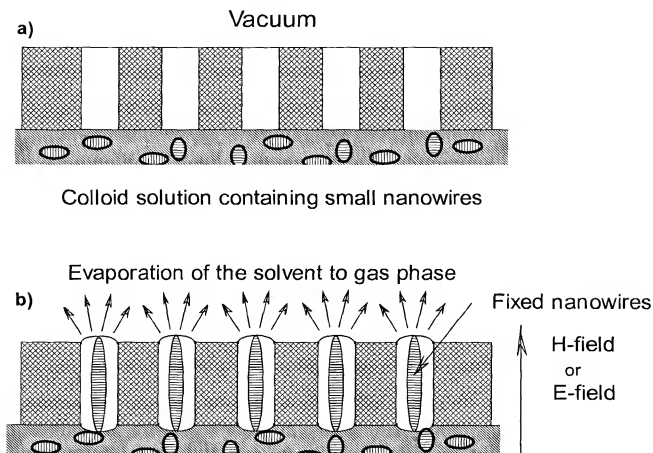
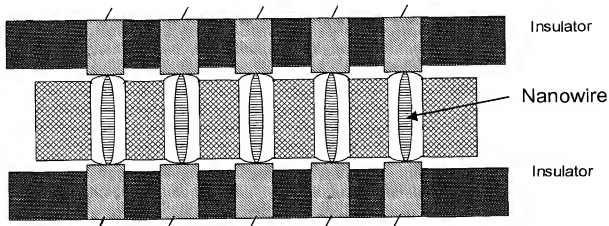


Figure 18

Individual metallic contact pads to be connected with first electronic circuitry



Individual metallic contact pads to be connected with second electronic circuitry

Figure 19

Conducting pads to be connected with electronic circuitry

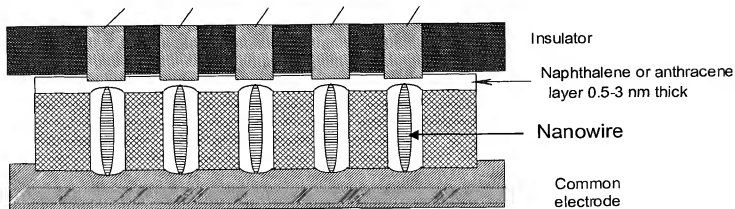


Figure 20

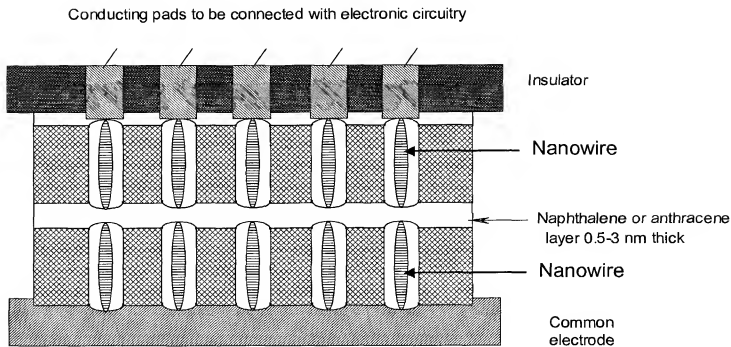


Figure 21

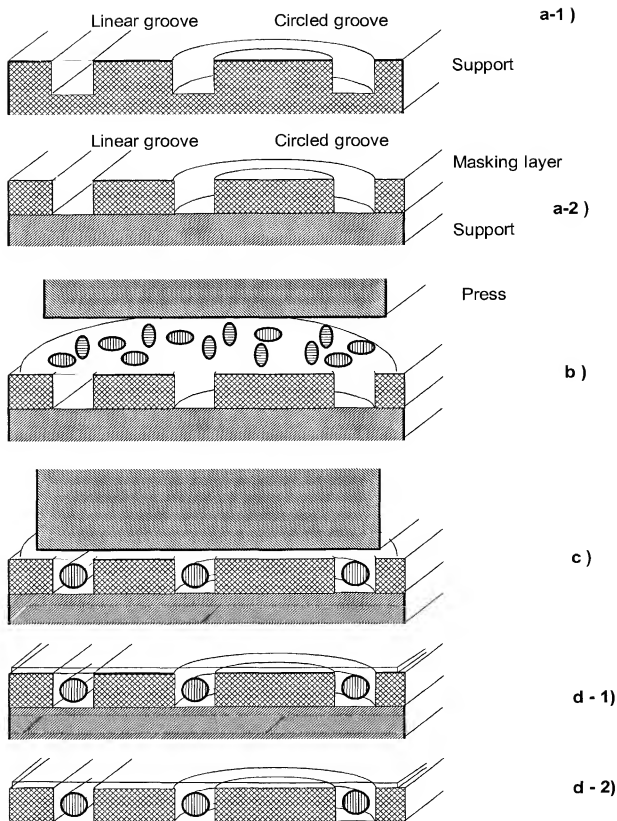


Figure 22

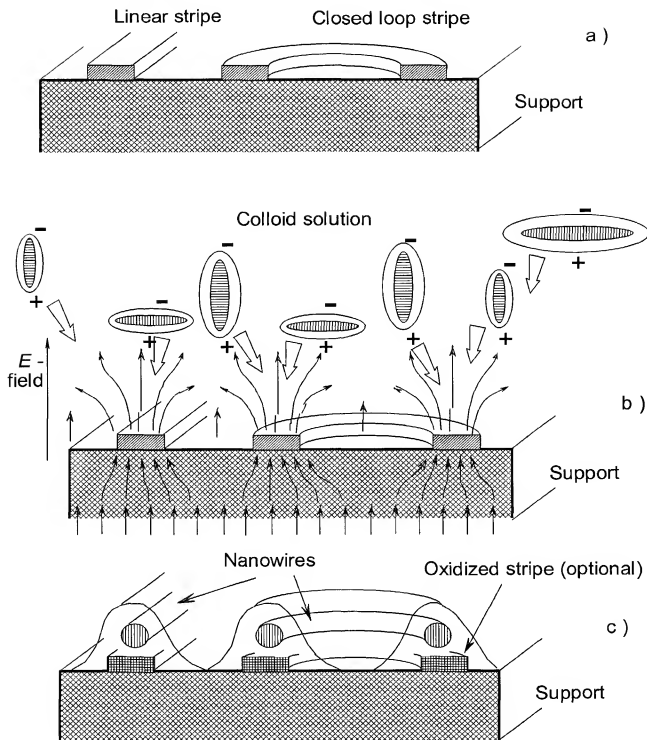


Figure 23

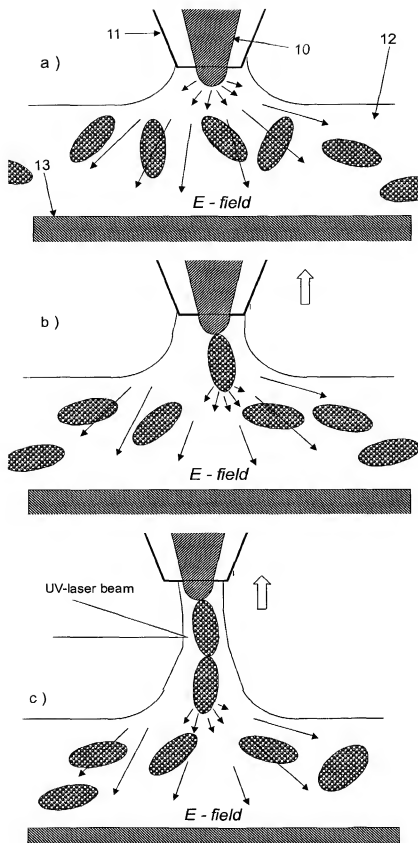


Figure 24